规格书编号

SPEC NO: HDF549.5E5S4SP00

产品规格书
SPECIFICATION

CUSTOMER 客 户：

PRODUCT 产 品：SAW FILTER

MODEL NO 型 号：HDF549.5E5-S4

MARKING 印 字：HDF4558

PREPARED 编 制： CHECKED 审 核：

APPROVED 批 准： D A T E 日 期：2015-3-5

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

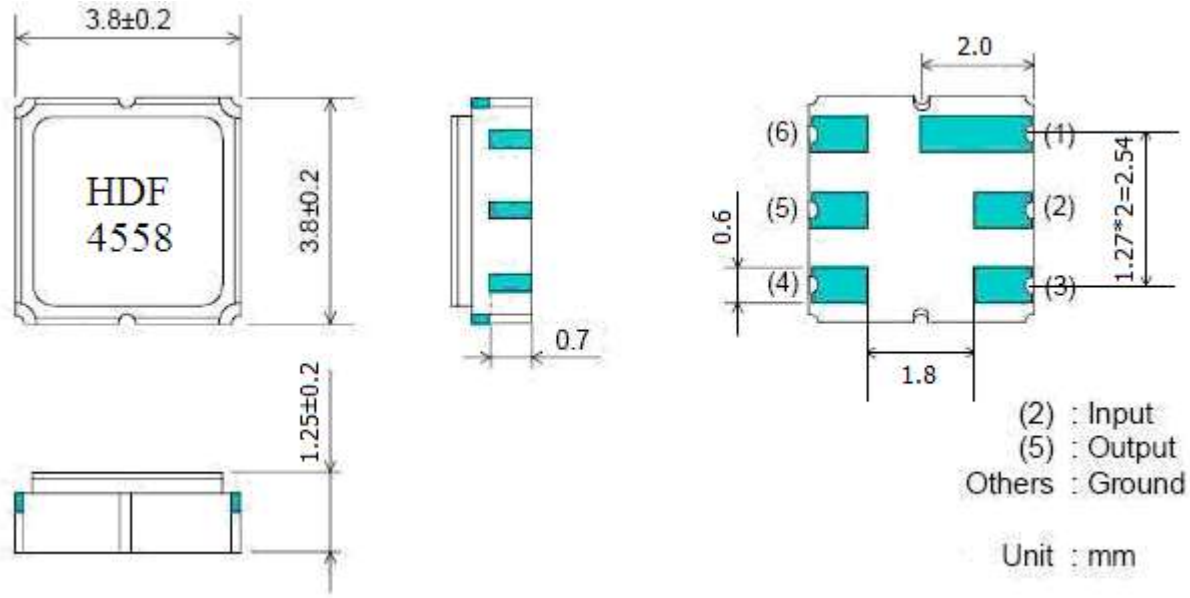
无锡市好达电子有限公司

Shoulder Electronics Limited

更改历史记录
History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

1. Package Dimension



2. Performance

2.1 Maximum Rating

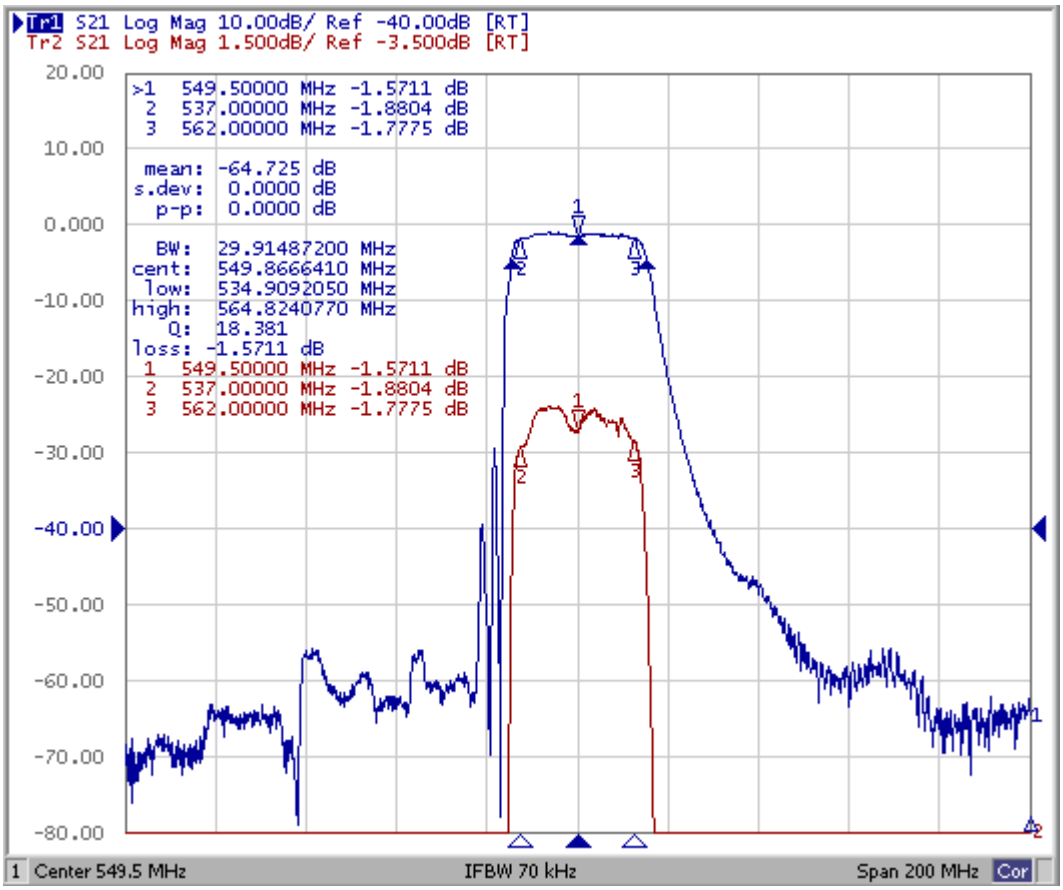
Items	Rating	unit
Maximum Working Voltage	10	V_{dc}
Maximum Working Power	10	dBm
Operating Temperature Range	-40 ~ +85	℃
Storage Temperature Range	-40 ~ +85	℃

2.2 Electronic Characteristics

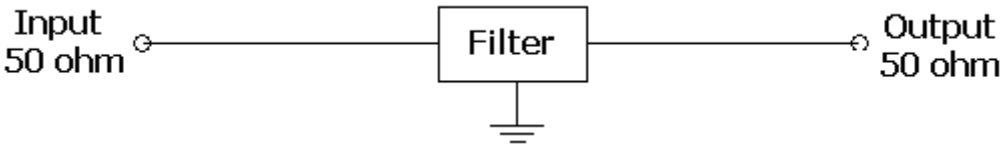
（at 25℃±5℃）

	Unit	Minimum	Typical	Maximum
Center Frequency Fc	MHz	547.5	549.5	551.5
Insertion Loss (549.5 MHz)	dB		1.5	3.0
-1dB bandwidth	MHz	25	29.9	-
Attenuation DC~520 MHz 600~1000 MHz	dB	 45 45	 55 55	-
Input/Output Impedance	Ohms		50	

2.3 Frequency Characteristics



3. Test Circuit



4. ENVIRONMENTAL CHARACTERISTICS

4.1 High temperature exposure

Subject the device to +85℃ for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

4.2 Low temperature exposure

Subject the device to -40℃ for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

4.3 Temperature cycling

Subject the device to a low temperature of -40℃ for 30 minutes. Following by a high temperature of +85℃ for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2-2.

4.4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260℃ ±10℃ for

10±1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2-2.

4.5 Solderability

Subject the device terminals into the solder bath at 245℃ ±5℃ for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2-2.

4.6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in2-2.

4.7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2-2.

5. REMARK

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.